

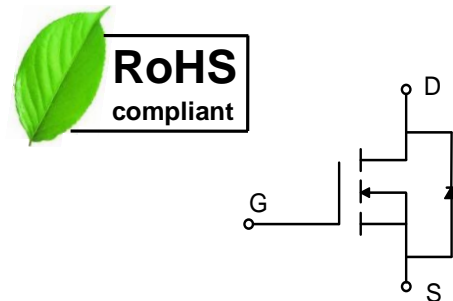
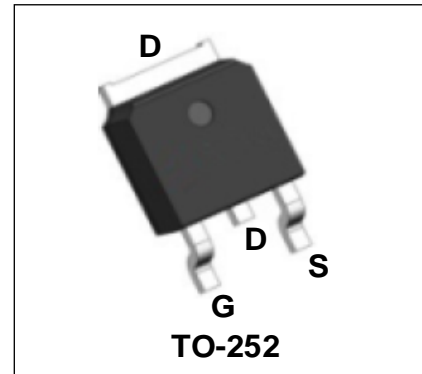
## 40V N-Channel Enhancement Mode Power MOSFET

### Description

WMO60N04T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

### Features

- $V_{DS} = 40V$ ,  $I_D = 60A$   
 $R_{DS(on)} < 7m\Omega @ V_{GS} = 10V$   
 $R_{DS(on)} < 12m\Omega @ V_{GS} = 4.5V$
- High Density Cell Design
- Fully Characterized Avalanche Voltage and Current
- Low  $R_{DS(on)}$
- Good Stability and Uniformity with High EAS
- Excellent Package for Good Heat Dissipation



### Applications

- Load Switch
- Uninterruptible Power Supply
- Hard Switched and High Frequency Circuits

### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current@10V <sup>1</sup>	$I_D$	$T_C=25^\circ C$	60
		$T_C=100^\circ C$	42
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	240	A
Single Pulse Avalanche Energy <sup>3</sup>	<b>EAS</b>	193.2	mJ
Avalanche Current	$I_{AS}$	27.8	A
Total Power Dissipation <sup>4</sup>	$T_C=25^\circ C$	$P_D$	55
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Case <sup>1</sup>	$R_{\theta JC}$	2.7	$^\circ C/W$

**Electrical Characteristics** T<sub>c</sub> = 25°C, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	<b>V<sub>(BR)DSS</sub></b>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	40	-	-	V
Gate-body Leakage current	<b>I<sub>GSS</sub></b>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	<b>I<sub>DSS</sub></b>	T <sub>J</sub> =25°C V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate-Threshold Voltage	<b>V<sub>GS(th)</sub></b>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.1	1.7	2.5	V
Drain-Source on-Resistance <sup>2</sup>	<b>R<sub>DS(on)</sub></b>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A	-	5.4	7	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	-	9.3	12	
Forward Transconductance	<b>g<sub>fs</sub></b>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 15A	-	28	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	<b>C<sub>iss</sub></b>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, f = 1MHz	-	2400	-	pF
Output Capacitance	<b>C<sub>oss</sub></b>		-	192	-	
Reverse Transfer Capacitance	<b>C<sub>rss</sub></b>		-	160	-	
<b>Switching Characteristics</b>						
Total Gate Charge	<b>Q<sub>g</sub></b>	V <sub>GS</sub> = 10, V <sub>DS</sub> = 20V, I <sub>D</sub> = 30A	-	46	-	nC
Gate-Source Charge	<b>Q<sub>gs</sub></b>		-	5.8	-	
Gate-Drain Charge	<b>Q<sub>gd</sub></b>		-	12.5	-	
Turn-on Delay Time	<b>t<sub>d(on)</sub></b>	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 20V, R <sub>G</sub> = 3Ω, R <sub>L</sub> = 1Ω, I <sub>D</sub> = 30A	-	12.5	-	nS
Rise Time	<b>t<sub>r</sub></b>		-	36	-	
Turn-off Delay Time	<b>t<sub>d(off)</sub></b>		-	45	-	
Fall Time	<b>t<sub>f</sub></b>		-	14.4	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>2</sup>	<b>V<sub>SD</sub></b>	I <sub>S</sub> = 30A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>	<b>I<sub>S</sub></b>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	60	A
Body Diode Reverse Recovery Time	<b>t<sub>rr</sub></b>	I <sub>F</sub> = 20A, dI/dt = 100A/μs	-	14.5	-	nS
Body Diode Reverse Recovery Charge	<b>Q<sub>rr</sub></b>		-	5.8	-	nC

## Notes:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=30V, V<sub>GS</sub>=10V, L=0.5mH, I<sub>AS</sub>=27.8A
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

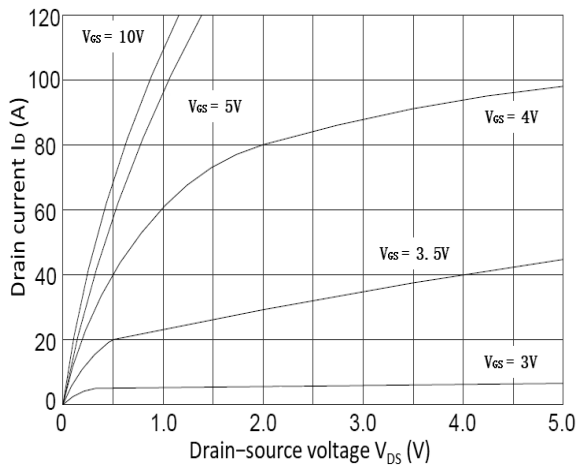


Figure 1. Output Characteristics

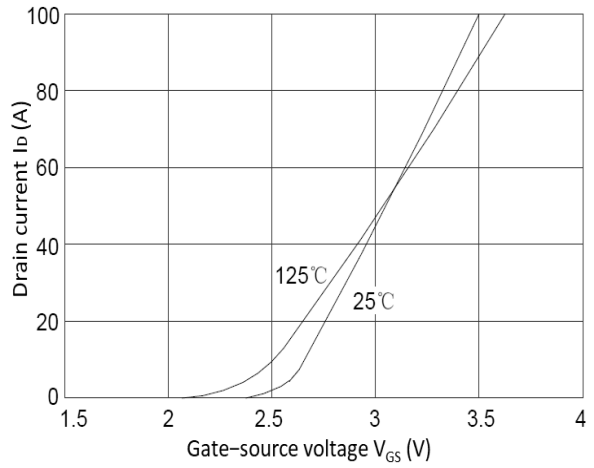


Figure 2. Transfer Characteristics

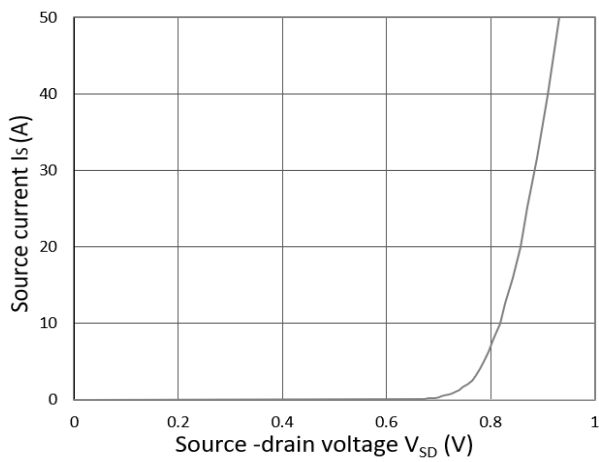


Figure 3. Forward Characteristics of Reverse

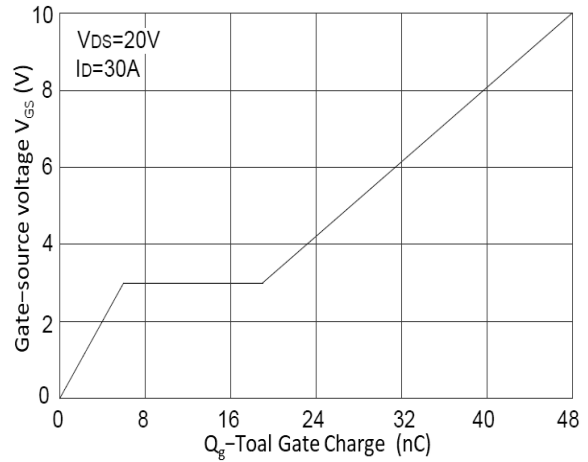


Figure 4. Gate Charge Characteristics

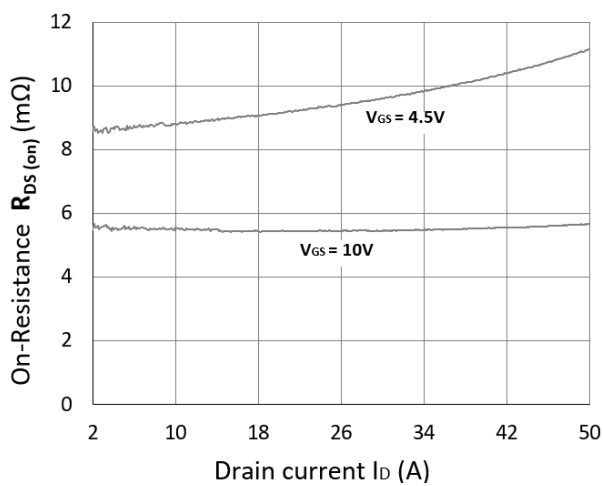


Figure 5.  $R_{DS(on)}$  vs.  $I_D$

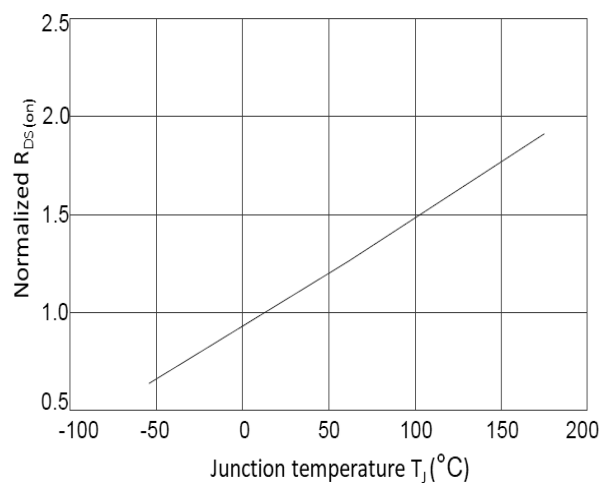


Figure 6. Normalized  $R_{DS(on)}$  vs.  $T_J$

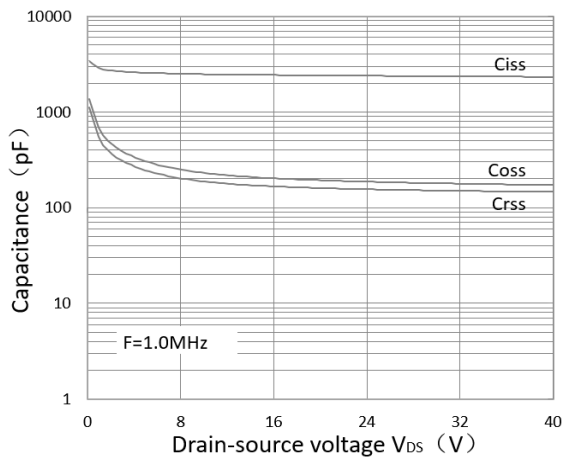


Figure 7. Capacitance Characteristics

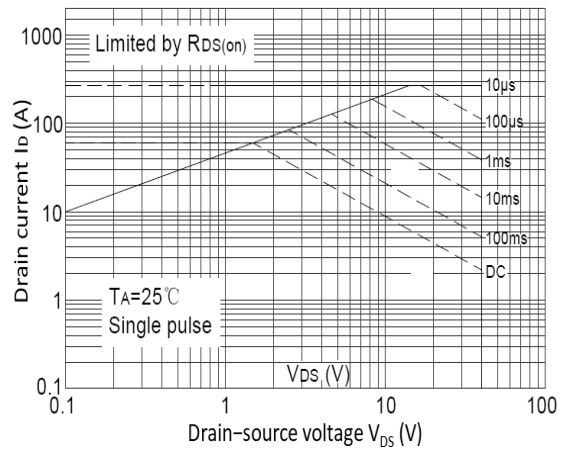


Figure 8. Safe Operating Area

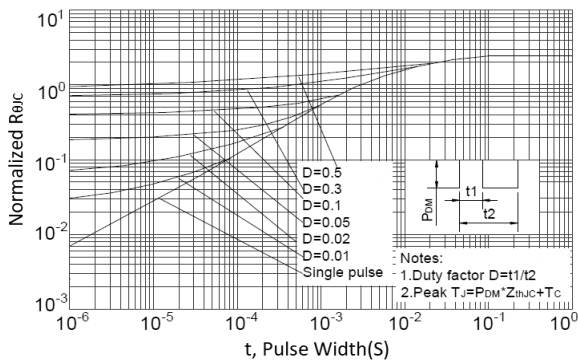


Figure 9. Normalized Maximum Transient

Thermal Impedance

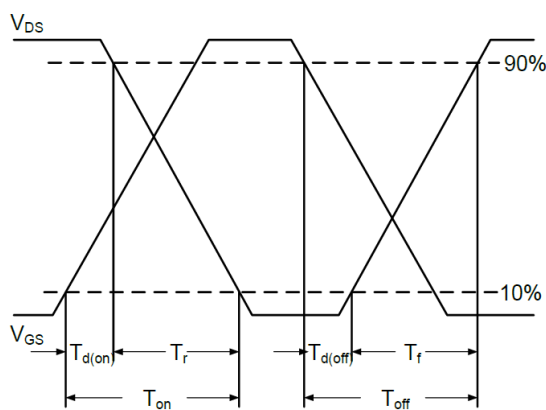


Figure 10. Switching Time Waveform

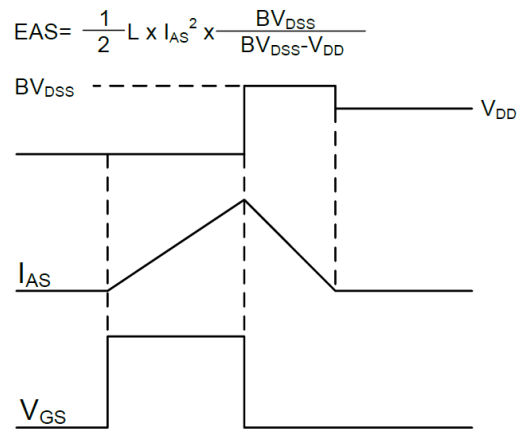
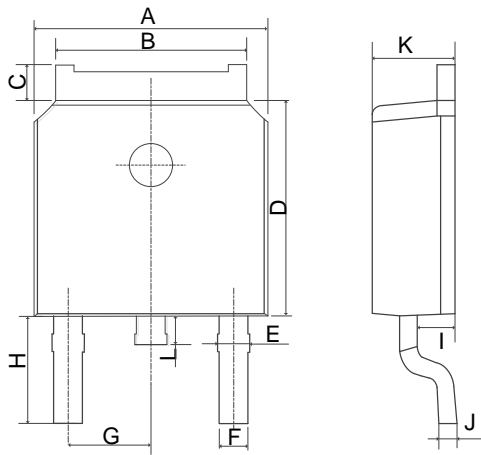


Figure 11. Unclamped Inductive Switching Waveform

## Mechanical Dimensions for TO-252



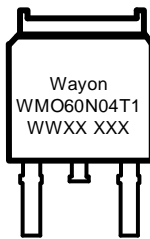
## COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	6.40	6.80
B	5.13	5.50
C	0.88	1.28
D	5.90	6.22
E	0.68	1.10
F	0.68	0.91
G	2.29REF	
H	2.90REF	
I	0.85	1.17
J	0.51REF	
K	2.10	2.50
L	0.40	1.00

## Ordering Information

Part	Package	Marking	Packing method
WMO60N04T1	TO-252	WMO60N04T1	Tape and Reel

## Marking Information



WMO60N04T1 = Device code

WWXX XXX= Date code

## Contact Information

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